



BOARD LEVEL COOLING – 10-6327

10-6327 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. This heat sink is mounted with nylon push pins with springs. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
10-6327-01G	BGA, FPGA

HEAT SINK DETAILS

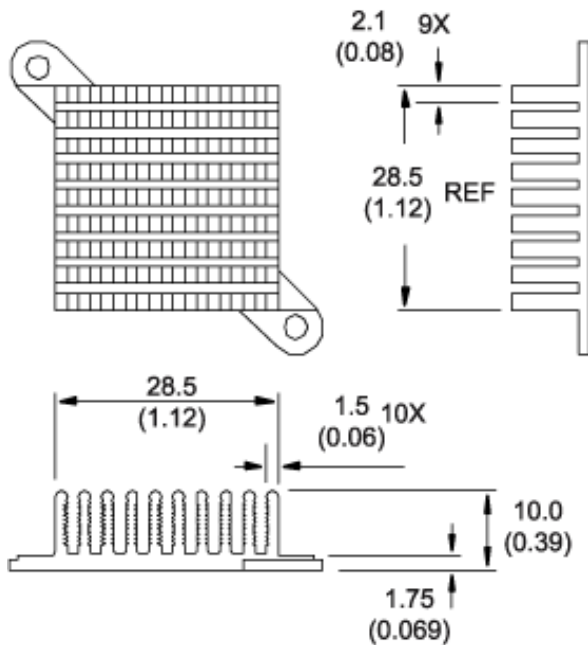
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Push Pin
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	28.50
Heat Sink Length (mm)	28.50
Heat Sink Height (mm)	10.00
Heat Sink Mounting Direction	Horizontal, Vertical

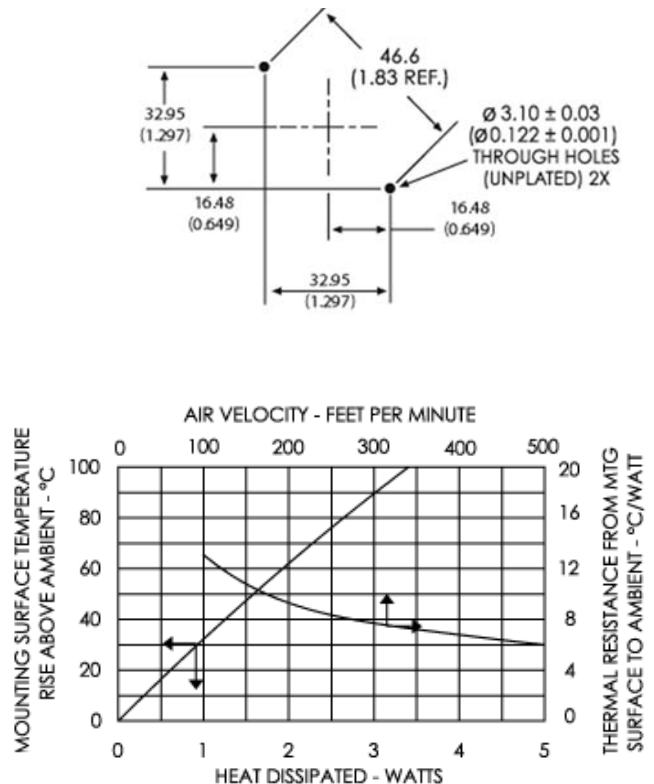


MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Mounting Details:



USA: 1.855.322.2843
 EUROPE: 39.051.764002
 ASIA: 86.21.6115.2000 x8122